**修改说明：以下为根据现有网站设计的部分美化意见。紫色字体部分请完全原样复制到网页。**

**Homepage修改建议：**

1. 导航条title请与LOGO下方对齐；

搜索框文暂时去掉

1. Slideshow图片请宽度加长（参考RE）
2. Slideshow文字：（图片请参照微信）

* Largest Source of EOL Products in Asia 图片1
* Hermetic Assembly for High Reliability and Demanding Environment 图片2
* Wide Variety of Testing Capabilities 图片3

1. POLICY暂时不放在主页上

**DIE BANK修改意见：**

参考链接<https://www.rocelec.com/products/authorized-distribution>

1. 文字：

**The Largest Continues Source of Dies in Asia. 粗体**

100% traceable, certified and guaranteed.

* Over 13,000 part numbers in stock.
* Over 65,000 square feet of class 10,000 clean room.
* Devices in hermetically sealed cabinets for storage.

1. 请在Sign Up Button 里写：

**SIGN UP FOR DIE BANK INVENTORY UPDATES 粗体**

1. Sign Up 信息栏参考：<https://www.rocelec.com/login> 的右边框

信息栏顺序为：

**Email Address\*, First Name\*, Last Name\*, Position, Company Name\*, Company Website** 粗体 (\*为必填)

**PRODUCTS 修改意见:**

1. 四个分类目前点击没有变化—分类请放5个（Memory, Linear, Logic ,Opto, Diodes/Transistors）都请大写
2. **在每个产品页面加一段话：**

**MEMORY:**

Offers HiRel memory products in monolithic form 16K to 4Mb and MCMs or modules up to 64Gb in all package types (-55°C to +125°C) and special specifications to +175°C.

The largest range of HiRel replacement SRAM, EEPROM, FLASH and UVEPROM memory in standard and custom packages. Manufactured under MIL-PRF-53835 and tested in accordance with MIL-STD-883, M5004 with optional B, C, D, group testing.

**LINEAR:**

Extensive range of Linear Products: Op-Amps, Comparators, Amplifiers, Comparators, References and more. Utilizing OEM Die/Wafers inventory and housed in controlled storage units. Custom manufactured in ceramic and metal can. Guaranteed to meet original OEM or custom specification. Mil-prf-38535. Environment and Functionality tested (-55°C to +125°C) in accordance with Mil-Std-883 M5004. Group B,C,D testing and SnPb or Pb free options are available.

**LOGIC:**

A comprehensive range of Logic gates in various technologies including: HC, HCT, FCT etc. Utilizing Die/Wafers inventory from different OEM’s we can manufacture and test devices to original data sheets in most package types and to most temperature and screening levels, whether they are simple gates or complex drivers. Specific custom circuits can also designed and packaged using: Modules, MCM’s or Structured ASIC’s. Packages include Hermetic, Ceramic (-55°C to +125°C). All products can be tested in accordance with Mil-Std-883 with Group testing to B,C,D optional.

**OPTO:**

BI offers comprehensive range of OPTO parts including photo diodes, photo transistors, optocouplers and many more. Utilizing Die/Wafers inventory combined with die purchased from official OEM sources, BI can manufacture with the highest level of quality you would expect from the OEM. Offering a 100% guarantee to meet the original specification, and we work closely with the customer to solve OPTO obsolescence issue.

**DIODES and TRANSISTORS:**

Force Technologies can provide virtually any diode or transistor for your HiRel application, critical testing and design support. Equivalents which conform to JAN, JANTX or JANTXV screening are possible.

A large range of products for obsolete Diodes applications is available, including: varactor diodes, TVS diodes, Tuning diodes, abrupt diodes, hyper abrupt diodes, Microwave, Zener diodes and rectifier diodes. We manufacture in glass, ceramic and surface mount SOT, SOD and MELF packages. Custom specifications are available。

Available transistors include small signal transistors, Darlington transistors, high voltage transistors and high-power transistors (to 300 Watts). Screening options include PIND, B.I. (up to 100A) and environmental testing. We offer standard and custom packaging for obsolete parts. Devices manufactured and tested to the highest specifications. Group A/B/C/D testing is available.

1. 左边导航条请往左移，数据请平铺 左边空白太大
2. 开头FT没有全部改成BI(之前说的是HR不好意思)
3. DATA请按照Part number去重
4. 请给data们加个表格框，现在不够工整
5. Title名称顺序如下：（加粗、字体加大）

HR Part Number\Generic\Size\Org\Memory Speed\Description\ Alternative Part Number 1\ Alternative Part Number 2

8. 没有搜索框：每个产品页面都请加个模糊搜索框，和主页类似

🡪 Search the largest semiconductor inventory in Asia…

**Service** 请把Logistic 暂时停掉

**Manufacturing Service**

**Wafer Processing**

Our in-house capabilities provide quick-turn wafer processing for Wafer Thinning, Back Metallization, Probing, Sawing, Visual Inspection, Pick and Place.

**Finish Product Design**

BI can re-create the original device. The end product is a form, fit, and functional replacement guaranteed to the original data sheet performance.

**Test**

Our proven test protocol ensures the highest test quality with accuracy guaranteed; offering a wide variety of capabilities across multiple test platforms.

**About Us**

Headquartered in Singapore. BI Components strives to be a world leading independent distributor specialist, offering comprehensive wafer and bare die inventory for hybrid IC and multi-chip module manufacturers in global marketplace. BI's extensive product line of hi-reliability bare die components, has made the company one the top and largest bare die supplier of choice for Aerospace, Defense, Space, Medical, and Industrial markets in Asia and worldwide.

The corporate facility is equipped with ESD protected class 10,000 cleanrooms, nitrogen-filled and hermetically sealed stored inventory. Combined with strict ISO9100 quality systems, our extensive inventory ensures quick delivery without compromise to quality. All dies are visually inspected to MIL-STD-833 methods and 100% probed. Aerospace-grade products are 100% screened and aging-tested.

Our services have grown more extensive and has been dedicated to multi-chip module (MCM), hybrid integrated circuit (HIC), chip-on-board (COB) and single-chip integrated circuit packaging solutions. With broadest offering of bare die products and value-added processing in the industry, BI Components became recognized as a leading bare die add value provider in Asian and global marketplace.

**Contact US**

参考链接：<https://www.rocelec.com/about/contact>

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Career子目录请去掉

**配图**

请按照微信发送的图片